

HEX Size	Part Number	V _{DS}	R _{DS(on)}	Die Outline Figure	Recommended Source Bonding Wire		Equivalent Device Type
					mils	mm	

HEXFET® Die

N-Channel

4.1	IRFC048	60	0.018	D24	20	0.15	IRFZ48
4	IRFCE40	800	2	D23	10	0.25	IRFPE40
3	IRFC430	500	1.5	D15	8	0.2	IRF830
3	IRFCC30	600	2.2	D16	8	0.2	IRFBC30
3	IRFCE30	800	3.2	D17	10	0.25	IRFBE30
3	IRFCF30	900	4	D17	10	0.25	IRFBF30
3	IRFC234	250	0.45	D14	8	0.2	IRF634
4	IRFC044	60	0.028	D19	20	0.15	IRFZ44
3	IRFC230	200	0.4	D14	8	0.2	IRF630
4	IRFC140	100	0.077	D20	15	0.38	IRF540
4	IRFC240	200	0.18	D21	15	0.38	IRF640
4	IRFC244	250	0.28	D21	15	0.38	IRF644
4	IRFC340	400	0.55	D22	12	0.3	IRF740
4	IRFC440	500	0.85	D22	12	0.3	IRF840
4.5	IRFC448	500	0.6	D25	12	0.3	IRFP448
1	IRFC014	60	0.2	D2	5	0.13	IRFZ14
3	IRFCG30	1000	5.6	D17	10	0.25	IRFBG30
2	IRFC224	250	1.1	D8	8	0.2	IRF624
1	IRFC110	100	0.54	D3	5	0.13	IRF510
1	IRFC210	200	1.5	D4	5	0.13	IRF610
1	IRFC214	250	2	D4	5	0.13	IRF614
1	IRFC310	400	3.6	D5	5	0.13	IRF710
2	IRFC024	60	0.1	D6	10	0.25	IRFZ24
3	IRFC330	400	1	D15	8	0.2	IRF730
2	IRFC220	200	0.8	D8	8	0.2	IRF620
4	IRFCF40	906	2.5	D23	10	0.25	IRFPF40
2	IRFC320	400	1.8	D9	8	0.2	IRF720

Common Characteristics: IDSS @ VDS 250µA

500nA

VGS(th) Standard gate: min 2V, max 4V with VDS=VGS, ID=250µA

VGS(th) Logic level: min 1V, max 2V with VDS=VGS, ID=250µA

RDS(on) Standard gate: measured @ VGS=10V

Logic level: measured @ VGS=5V

